LATVIAN CHIP
COMPETENCE
CENTRE

LCCC – Issue #1 (Summer 2025)

Welcome to the first issue of the LCCC Newsletter!

The Latvian Chip Competence Centre (LCCC) is set to strengthen Latvia's semiconductor ecosystem in line with the **EU Chips Act**. Over the next 48 months, LCCC will **support SMEs**, **advance microchip technology**, and **foster the growth of innovative tech startups** through targeted skill development activities.

The consortium of the LCCC project consists of two key academic institutions: **Riga Technical University (RTU)** and the **University of Latvia (UL)**. **RTU is the largest technical and engineering university in the Baltic States**, known for its expertise in cutting-edge fields such as photonics, microelectronics, and chip design. The university plays a central role in advancing Latvia's technological capabilities in the semiconductor sector. **UL is a national leader in quantum technologies**, with internationally recognised contributions to quantum algorithms, quantum electronic devices, and quantum communication systems. Its research activities in these areas directly support the project's goal of driving forward semiconductor innovation and strengthening Europe's position in the global microchip market.

This newsletter keeps you informed about key project milestones, upcoming events, partner insights, and opportunities to get involved.

Recent events

Baltic Microchip Leaders Meet at LCCC s First Microchip Breakfast

On 16 May, the **Latvian Chip Competence Centre** hosted its first-ever **Microchip Breakfast** as a side event of **Deep Tech Atelier**, in collaboration with **LIAA**.
The event brought together experts from government, academia, industry, and investment to discuss the future of the Baltic semiconductor ecosystem. Notably, it marked **the first in-person meeting of all three Baltic Microchip Competence Centres** — from Latvia, Estonia, and Lithuania.

Short presentations were delivered by **Haralds Abolins** (Semiconductor Strategy Manager, Latvian Microchip Competence Centre), **Jaan Raik** (Coordinator of the Estonian CCC at EIS), and **Saulius Tumenas** (Head of the Semiconductor Optics Laboratory, FTMC).

The morning concluded with an open discussion and informal networking, highlighting the importance of cross-border collaboration and the human factor in driving deep tech innovation.

Latvia Strengthens Semiconductor Ties During Delegation Visit to Germany

In May, from Berlin to Dresden, a **Latvian delegation** representing **Riga Technical University**, the **University of Latvia**, and leading tech companies embarked on a strategic visit to **Germany's top semiconductor hubs** to foster cooperation and gain insights for **the development of the Latvian Chip Competence Centre (LCCC)**.

Day 1 in Berlin focused on innovation, integration, and policy. The delegation met with the **Fraunhofer-Gesellschaft**, discussing chip packaging and innovation strategies. At **Bitkom**, participants joined the Semiconductor Ecosystem & Technology Working Group, learning about Germany's national semiconductor strategy and future fields like photonics and quantum technologies.

Day 2 in Dresden – Europe's largest microelectronics cluster – began at the **Barkhausen Institut**, where research into secure and energy-efficient IoT systems was presented. At **X-FAB**, a leading semiconductor foundry, the group experienced precision chip manufacturing firsthand during a cleanroom tour.

The visit concluded with presentations by **Silicon Saxony, Saxony Trade & Invest Corp.,** and **IHK Dresden**, showcasing the strength of the region's semiconductor ecosystem. Latvian representatives shared Latvia's growing role in the sector and the vision of LCCC to support Baltic-wide collaboration and innovation.

Coming Soon Events

Online workshop on **Microelectronics for 6G - Front End Module**

📅 16 September, Tuesday
09:15 - 12:30 (CET)
Registration: **https://lnkd.in/e2FPHDBn**

The Smart Networks and Services Joint Undertaking invites experts to join an important **online workshop** focused on microelectronics components for 6G front-end modules. This event will address technological needs and priorities for inclusion in the Chips JU Work Programme 2026.

Save the Date: Techritory Forum 2025 in Riga

The Latvian Chip Competence Centre (LCCC) will take part in **Techritory Forum 2025**, showcasing Latvia's advancements in semiconductor research and innovation and contributing to Europe's digital and chip sovereignty ecosystem.

Techritory Forum 2025 will take place on **22–23 October 2025** at the **ATTA Centre in Riga, Latvia.**

This is a premier opportunity to engage with stakeholders shaping Europe's digital future, explore cutting-edge technologies, and support strategic cooperation across the semiconductor and digital sectors.

Register for free and stay tuned for updates on the agenda, LCCC's role, and networking opportunities.

🔗 More info available via the official website: techritory.com

Nordic Chip Summit 2025 to Unite Europe's Semiconductor and Quantum Leaders

The Nordic Chip Summit 2025 will take place on **10 November 2025** at the **Dipoli Conference Centre** in **Espoo, Finland**, bringing together key actors from across Europe’s semiconductor, quantum, and deep tech ecosystems.

Powered by Kvanttinova, the leading Nordic innovation hub, the event will gather **representatives from**:

- Semiconductor and quantum-focused companies
- Research and Technology Organisations
- Nordic universities and educational institutions
- European Chip Competence Centres
- Policymakers and innovation enablers

With a programme of high-profile keynotes, targeted sessions, and collaborative networking, the summit aims to shape Europe’s vision for semiconductor and quantum technologies. Participants will exchange insights, spark new ideas, and strengthen cooperation across research, education, and industry.
This is a unique opportunity to build partnerships and contribute to Europe’s deep-tech future.

🔗 **More info** will be available soon: https://kvanttinova.fi/

Save the Date: European Forum for Electronic Components and Systems (EFECS) 2025 in Malta

The European Forum for Electronic Components and Systems (EFECS) 2025 will take place on **3–4 December 2025** at the **Hilton Hotel in St. Julian’s, Malta.** EFECS is Europe's flagship event dedicated to the entire electronic components and systems (ECS) value chain.

What to Expect:

- Keynote presentations and panel discussions covering hot topics such as quantum technologies, cybersecurity, AI.

- Networking with over 700 stakeholders from across Europe’s semiconductor and ECS sectors—including industry leaders, policymakers, researchers, and funding agencies.
- Insights into the progress and future direction of the Chips JU mission and the broader electronic components and systems ecosystem.

This is a unique opportunity to connect with key players in Europe’s chip ecosystem, stay informed on breakthrough technologies, and contribute to discussions shaping Europe's technological sovereignty and industrial resilience.

Registration opens soon: https://ipcei-me-ct.eu/events/european-forum-for-electronic-components-and-systems-2025/

Call for proposal

Open Call: Low-Power Edge AI Chips – Now Accepting Proposals

📅 **Deadline:** 17 September 2025

The Chips Joint Undertaking under Horizon Europe has launched a Coordination and Support Action aimed at reinforcing EU–Japan cooperation in the semiconductor sector.

What is this call about?

This call supports stronger EU–Japan collaboration in the semiconductor sector. It aims to coordinate research and innovation activities, with a focus on lifecycle assessment in chip manufacturing. This action will promote research exchange, build the basis for future joint R&I initiatives, and foster talent mobility between academia and industry across both regions.

Full details here

Open Call: EU–Japan Semiconductor Collaboration (HORIZON-JU-CHIPS-2025-CSA-JPN)

📅 **Deadline:** 17 September 2025

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Open Call: Accelerator for Advanced Strained Silicon-on-Insulator Substrates

Deadline: 20 November 2025

What is this call about?

This funding opportunity is part of the Digital Europe Programme under the Chips Joint Undertaking initiative. The call supports the development of a sustainable accelerator, accessible to all European stakeholders, for advanced strained silicon-on-insulator (sSOI) technologies. This includes enhancing access to sSOI substrates, scaling industrial production, and standardizing design tools.

Full details here

Beyond Chips Podcast by Chips Joint Undertaking

The Chips Joint Undertaking has launched its official podcast – **Beyond Chips** – offering monthly insights into Europe’s semiconductor ecosystem.

New episodes drop **every first Wednesday of the month**, featuring voices from industry, research, and policy.

The first two episodes are already available and dive into key challenges, opportunities, and innovations shaping Europe's chips strategy.

Tune in and stay informed: EPISODE 1, EPISODE 2.

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